

BQ296xxx 2/3/4 直列セル・リチウムイオン・バッテリー向け過電圧保護、安定化出力電源付き

1 特長

- 2/3/4 直列セル過電圧保護 (OVP)
- FET 駆動出力をトリガするための固定遅延タイム (3 秒、4 秒、5.5 秒、6.5 秒のいずれかを選択可能)
- 出荷時に OVP スレッシュホールドをプログラム (スレッシュホールドの範囲は 3.85V~4.6V)
- 出力オプション: アクティブ HIGH
- 高精度の過電圧保護: $\pm 10\text{mV}$
- 自己ディセーブル、外部イネーブル / ディスエーブル制御付きの安定化電源出力
 - オプション: 3.3V、2.5V、1.8V (BQ2961)
 - オプション: 3.3V、3.15V、3.0V (BQ2962)
- 低消費電力 $I_{CC} \approx 4\mu\text{A}$ ($V_{\text{CELL(ALL)}} < V_{\text{PROTECT}}$)
- 安定化出力を無効にすることで消費電力をさらに低減、 $I_{CC} \approx 1.2\mu\text{A}$
- セル入力あたりのリーク電流が低い: 100nA 未満
- 小さいパッケージ占有面積
 - 8 ピン WSON (2mm × 2mm)

2 アプリケーション

- ノート PC
- ウルトラブック
- 医療用
- UPS バッテリー・バックアップ

3 概要

BQ296xxx ファミリーは、リチウムイオン・バッテリー・バック・アプリケーション向けの、2mA 安定化出力電源付きの高精度低消費電力の過電圧保護素子です。

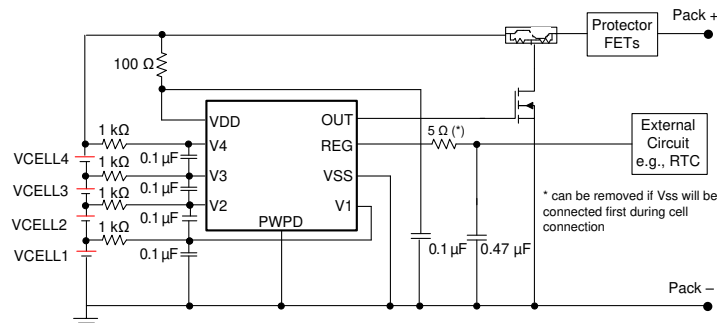
2~4 直列セル・スタック内の各セルの過電圧状態を個別に監視します。いずれかのセルで過電圧状態が検出されると、内部固定遅延タイムが起動します。遅延タイムがタイムアウトすると、過電圧状態が発生したことを示すために出力ピンがアクティブ状態にトリガされます。

安定化出力電源は、リアルタイム・クロック (RTC) 発振器などの常時オン回路を駆動するために最大 2mA の電流を出力します。BQ296xxx ファミリーは、いずれかのセル電圧が特定のスレッシュホールドを下回ると安定化出力をオフにする自己ディセーブル機能を備えており、それによってバッテリーの消耗を防止できます。また、安定化出力のイネーブル / ディセーブルを外部から制御することもできます。

製品情報

| 部品番号 ⁽¹⁾ | パッケージ | 本体サイズ (公称) |
|---------------------|----------|-----------------|
| BQ2961 | WSON (8) | 2.00mm × 2.00mm |
| BQ2962 | | |

- (1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



概略回路図



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

| | |
|---|-------------|
| Changes from Revision S (June 2022) to Revision T (August 2022) | Page |
| • Noted in the Device Comparison Table that the increased UV range is for future BQ2962 devices only..... | 3 |
| • Clarified future BQ2962 options..... | 9 |
| Changes from Revision R (April 2022) to Revision S (June 2022) | Page |
| • Increased the UV range for future BQ2962 device in the Device Comparison Table | 3 |
| Changes from Revision Q (January 2022) to Revision R (April 2022) | Page |
| • Changed the BQ296234 device to Production Data in the Device Comparison Table | 3 |
| Changes from Revision P (August 2021) to Revision Q (January 2022) | Page |
| • Added the BQ296234 PRODUCT PREVIEW device to the Device Comparison Table | 3 |
| Changes from Revision O (July 2021) to Revision P (August 2021) | Page |
| • Changed the BQ296227 and BQ296233 devices to Production Data in the Device Comparison Table | 3 |

5 Device Comparison Table

表 5-1. BQ2961 Device Options

| BQ2961 | OVP (V) | OVP DELAY (s) | UV (V) | LDO (V) |
|-------------------------|----------------------------|--------------------|--------------------------|---------------|
| BQ296100 | 4.35 | 6.5 | 2.5 | 3.3 |
| BQ296103 | 4.50 | 6.5 | 2.5 | 3.3 |
| BQ296106 | 4.45 | 6.5 | 2.8 | 3.3 |
| BQ296107 | 4.50 | 6.5 | 2.8 | 3.3 |
| BQ296111 | 4.45 | 4.0 | 2.5 | 3.3 |
| BQ296112 | 4.50 | 3.0 | 2.5 | 3.3 |
| BQ296113 | 4.35 | 3.0 | 2.5 | 3.3 |
| BQ296114 | 4.50 | 4.0 | 2.5 | 3.3 |
| BQ296115 | 4.25 | 6.5 | 2.0 | 2.5 |
| BQ296116 ⁽¹⁾ | 4.50 | 6.5 | 2.5 | 1.8 |
| BQ2961 | 3.85 V–4.60 V (50-mV step) | 3.0, 4.0, 5.5, 6.5 | 2.0 V–2.8 V (50-mV step) | 1.8, 2.5, 3.3 |

(1) PRODUCT PREVIEW. Contact TI for more information.

表 5-2. BQ2962 Device Options

| BQ2962 | OVP (V) | OVP DELAY (s) | UV (V) | LDO (V) |
|-----------------------|----------------------------|--------------------|--------------------------|--------------|
| BQ296202 | 4.45 | 6.5 | 2.5 | 3.3 |
| BQ296203 | 4.50 | 6.5 | 2.5 | 3.3 |
| BQ296212 | 4.50 | 3.0 | 2.5 | 3.3 |
| BQ296213 | 4.35 | 3.0 | 2.5 | 3.3 |
| BQ296215 | 4.50 | 6.5 | 2.5 | 3.0 |
| BQ296216 | 4.55 | 6.5 | 2.5 | 3.0 |
| BQ296217 | 4.55 | 6.5 | 2.8 | 3.3 |
| BQ296221 | 4.55 | 6.5 | 2.5 | 3.3 |
| BQ296222 | 4.50 | 6.5 | 3.0 | 3.0 |
| BQ296223 | 4.50 | 6.5 | 2.5 | 3.3 |
| BQ296224 | 4.50 | 6.5 | 2.5 | 3.0 |
| BQ296226 | 4.50 | 6.5 | 2.8 | 3.3 |
| BQ296227 | 4.55 | 6.5 | 2.8 | 3.3 |
| BQ296228 | 4.55 | 6.5 | 2.5 | 3.0 |
| bq296229 | 4.60 | 6.5 | 2.5 | 3.0 |
| BQ296230 | 4.35 | 6.5 | 3.0 | 3.0 |
| BQ296231 | 4.60 | 6.5 | 2.5 | 3.3 |
| BQ296232 | 4.55 | 6.5 | 3.0 | 3.0 |
| BQ296233 | 4.45 | 6.5 | 2.5 | 3.3 |
| BQ296234 | 4.60 | 6.5 | 3.0 | 3.0 |
| BQ2962 ⁽¹⁾ | 3.85 V–4.60 V (50-mV step) | 3.0, 4.0, 5.5, 6.5 | 2.0 V–3.5 V (50-mV step) | 3, 3.15, 3.3 |

(1) PRODUCT PREVIEW. Contact TI for more information.

6 Pin Configuration and Functions

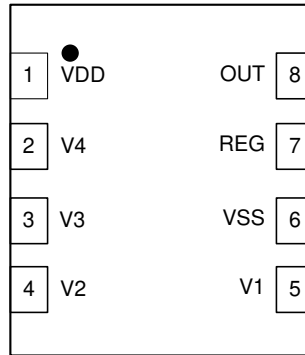


图 6-1. 2-Series to 4-Series BQ2961 (Top View)

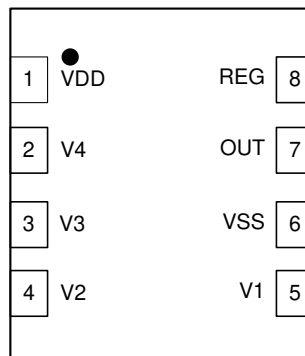


图 6-2. 2-Series to 4-Series BQ2962 (Top View)

表 6-1. Pin Functions

| PIN | | BQ2962 | TYPE ⁽¹⁾ | DESCRIPTION |
|--------|--------|--------|---------------------|---|
| NAME | BQ2961 | | | |
| OUT | 8 | 7 | OA | Analog output drive for an overvoltage fault signal; CMOS output high or open-drain active low |
| PWPD | 9 | 9 | P | TI recommends connecting the exposed pad to VSS on PCB. |
| REG | 7 | 8 | OA | Regulated supply output. Requires an external ceramic capacitor for stability |
| REG_EN | — | — | IA | Regulated supply output enable. A "high" to enable REG output and "low" to disable REG output |
| V1 | 5 | 5 | IA | Sense input for positive voltage of the lowest cell from the bottom of the stack |
| V2 | 4 | 4 | IA | Sense input for positive voltage of the second cell from the bottom of the stack |
| V3 | 3 | 3 | IA | Sense input for positive voltage of the third cell from the bottom of the stack |
| V4 | 2 | 2 | IA | Sense input for positive voltage of the fourth cell from the bottom of the stack |
| VDD | 1 | 1 | P | Power supply input |
| VSS | 6 | 6 | P | Electrically connected to integrated circuit ground and negative terminal of the lowest cell in the stack |

(1) IA = Analog input, OA = Analog Output, P = Power connection

7 Specifications

7.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|---|-------------------------------------|---------------------------------|-----|------|
| Supply voltage | VDD – VSS | –0.3 | 30 | V |
| Input voltage | V4 – V3, V3 – V2, V2 – V1, V1 – VSS | –0.3 | 30 | |
| | REG – VSS | –0.3 | 3.6 | |
| | REG_EN – VSS | –0.3 | 28 | |
| Output voltage | OUT – VSS | –0.3 | 30 | |
| Continuous total power dissipation, P _{TOT} | | See セクション 7.4 . | | |
| Lead temperature (soldering, 10 s), T _{SOLDER} | | 300 | 300 | °C |
| Storage temperature, T _{stg} | | –65 | 150 | °C |

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

7.2 ESD Ratings

| | | VALUE | UNIT |
|--|--|-------|------|
| V _(ESD) Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾ | 2000 | V |
| | Charged device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾ | 500 | |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted).

| | | MIN | NOM | MAX | UNIT |
|---|--|-----|-----|-----|------|
| Supply voltage, V _{DD} ⁽¹⁾ | Supply voltage, V _{DD} ⁽¹⁾ | 3 | | 20 | V |
| | Supply voltage, V _{DD} with REG output on | 4 | | | |
| Input voltage range | V _n – V _{n-1} , V1 – VSS | 0 | | 5 | V |
| | REG_EN | 0 | | 15 | V |
| Operating ambient temperature range, T _A | | –40 | | 110 | °C |

- (1) See [セクション 9.2](#).

7.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | BQ296xxx | UNIT |
|-------------------------------|--|------------|------|
| | | DSG (WSON) | |
| | | 8 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance | 62 | °C/W |
| R _{θJC(top)} | Junction-to-case(top) thermal resistance | 72 | °C/W |
| R _{θJB} | Junction-to-board thermal resistance | 32.5 | °C/W |
| Ψ _{JT} | Junction-to-top characterization parameter | 1.6 | °C/W |
| Ψ _{JB} | Junction-to-board characterization parameter | 33 | °C/W |
| R _{θJC(bot)} | Junction-to-case(bottom) thermal resistance | 10 | °C/W |

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Electrical Characteristics

Typical values stated where $T_A = 25^\circ\text{C}$ and $V_{DD} = 14.4\text{ V}$, MIN/MAX values stated where $T_A = -40^\circ\text{C}$ to $+110^\circ\text{C}$, and $V_{DD} = 3\text{ V}$ to 15 V (unless otherwise noted).

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT | |
|---|--|--|--|-----|-----|---------------|---------------|
| Voltage Protection Thresholds | | | | | | | |
| V_{OV} | $V_{(PROTECT)}$ Overvoltage Detection | $R_{IN} = 1\text{ k}\Omega$ | Applicable Voltage: 3.85 V to 4.6 V in 50-mV steps | | | V | |
| V_{HYS} | OV Detection Hysteresis | | 250 | 300 | 400 | mV | |
| V_{OA} | OV Detection Accuracy | $T_A = 25^\circ\text{C}$ | -10 | | 10 | mV | |
| $V_{OADRIFT}$ | OV Detection Accuracy Across Temperature | $T_A = -40^\circ\text{C}$ | -40 | | 40 | mV | |
| | | $T_A = 0^\circ\text{C}$ | -20 | | 20 | mV | |
| | | $T_A = 60^\circ\text{C}$ | -24 | | 24 | mV | |
| | | $T_A = 110^\circ\text{C}$ | -54 | | 54 | mV | |
| | | $T_A = 110^\circ\text{C}$ | -54 | | 54 | mV | |
| Supply and Leakage Current | | | | | | | |
| I_{DD} | Supply Current with REG on | $(V_n - V_{n-1}) = 2\text{ V}$ to 4.15 V , $n = 1$ to 4 , $V_{DD} = \text{top } V_n$ voltage ($V_1 - V_{SS}) > V_{UVREG}$, $I_{REG} = 0\text{ mA}$, | $T_A = 0^\circ\text{C}$ to 60°C | | 4 | 6 | μA |
| | | | $T_A = -40^\circ\text{C}$ to 110°C | | | 8 | μA |
| I_{DD} | Supply Current with REG off | $(V_n - V_{n-1}) = 2\text{ V}$ to 4.15 V , $n = 1$ to 4 , $V_{DD} = \text{top } V_n$ voltage ($V_1 - V_{SS}) < V_{UVREG}$ | $T_A = 0^\circ\text{C}$ to 60°C | | 1 | 2 | μA |
| | | | $T_A = -40^\circ\text{C}$ to 110°C | | | 4 | μA |
| I_{IN} | Input Current at V_x Pins | $(V_n - V_{n-1}) = (V_1 - V_{SS}) = 3.8\text{ V}$, $V_{DD} = \text{top } V_n$ voltage, $T_A = 25^\circ\text{C}$ | -0.1 | | 0.1 | μA | |
| Output Drive OUT, CMOS Active High | | | | | | | |
| V_{OUT} | Output Drive Voltage, Active High | $(V_n - V_{n-1})$ or $(V_1 - V_{SS}) > V_{OV}$, $I_{OH} = 100\text{ }\mu\text{A}$, $V_{DD} = \text{top } V_n$ voltage | 6 | 7 | 8 | V | |
| | | If three of four cells are short circuited, only one cell remains powered and $> V_{OV}$, $V_{DD} = V_n$ (the remaining cell voltage), $I_{OH} = 100\text{ }\mu\text{A}$ | VDD – 0.3 | | | V | |
| | | $(V_n - V_{n-1})$ and $(V_1 - V_{SS}) < V_{OV}$, $V_{DD} = \text{sum of the cell stack voltage}$, $I_{OL} = 100\text{ }\mu\text{A}$ measured into OUT pin | 250 | | 400 | mV | |
| I_{OUTH} | OUT Source Current (during OV) | $(V_n - V_{n-1})$, $(V_3 - V_2)$, or $(V_1 - V_{SS}) > V_{OV}$, $V_{DD} = \text{top } V_n$ voltage, forced OUT = 0 V, measured out of OUT pin | | | 4.5 | mA | |
| I_{OUTL} | OUT Sink Current (no OV) | $(V_n - V_{n-1})$ and $(V_1 - V_{SS}) < V_{OV}$, $V_{DD} = \text{top } V_n$ voltage, forced OUT = VDD, measured into OUT pin. Pull-up resistor $R_{PU} = 5\text{ k}\Omega$ to VDD | 0.5 | | 14 | mA | |
| Internal Fixed Delay Timer | | | | | | | |
| t_{DELAY} | OV Delay Time ⁽¹⁾ | Internal Fixed Delay, 3-s delay option | 2.4 | 3 | 3.6 | s | |
| | | Internal Fixed Delay, 4-s delay option | 3.2 | 4 | 4.8 | s | |
| | | Internal Fixed Delay, 5.5-s delay option | 4.4 | 5.5 | 6.6 | s | |
| | | Internal Fixed Delay, 6.5-s delay option | 5.2 | 6.5 | 7.8 | s | |
| t_{DELAY_CTM} | Fault Detection Delay Time in Test Mode OV Delay Time | Internal Fixed Delay | | 15 | | ms | |
| t_{DELAY_RESET} | OV delay timer count reset time; t_{DELAY} resets when the cell voltage falls below V_{OV} for t_{DELAY_RESET} . ⁽¹⁾ | Internal Fixed Delay | | 0.6 | | ms | |

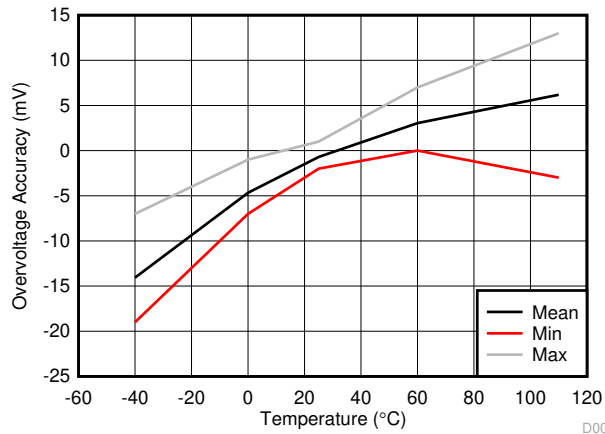
7.5 Electrical Characteristics (continued)

Typical values stated where $T_A = 25^\circ\text{C}$ and $V_{DD} = 14.4\text{ V}$, MIN/MAX values stated where $T_A = -40^\circ\text{C}$ to $+110^\circ\text{C}$, and $V_{DD} = 3\text{ V}$ to 15 V (unless otherwise noted).

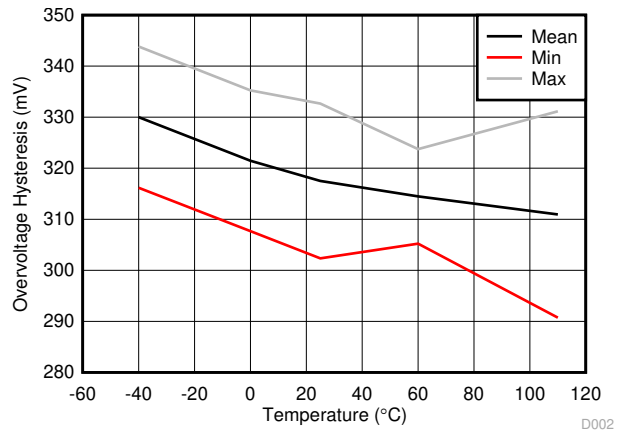
| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT | |
|---|--|--|---|-------|-------|---------------|---|
| Regulated Supply Output, REG | | | | | | | |
| V_{REG} | REG Supply at 500 μA load | $V_{DD} \geq 4\text{ V}$, $I_{REG} = 500\ \mu\text{A}$, $C_{REG} = 0.47\ \mu\text{F}$ | $V_{REG} = 3.3\text{ V}$, | 3.234 | 3.300 | 3.366 | V |
| | | | $V_{REG} = 3.15\text{ V}$, BQ2962 | 3.087 | 3.150 | 3.213 | |
| | | | $V_{REG} = 3.0\text{ V}$, BQ2962 | 2.940 | 3.000 | 3.060 | |
| | | | $V_{REG} = 2.5\text{ V}$, BQ2961 | 2.450 | 2.500 | 2.550 | |
| | | | $V_{REG} = 1.8\text{ V}$, BQ2961 | 1.764 | 1.800 | 1.836 | |
| V_{REG} | REG Supply from 0 to 2 mA load | $V_{DD} \geq 4\text{ V}$, $I_{REG} = 0\ \mu\text{A}$ to 2 mA, $C_{REG} = 0.47\ \mu\text{F}$ | $V_{REG} = 3.3\text{ V}$, BQ2961, BQ2962 | 3.200 | 3.300 | 3.400 | V |
| | | | $V_{REG} = 3.15\text{ V}$, BQ2962 | 3.050 | 3.150 | 3.250 | |
| | | | $V_{REG} = 3.0\text{ V}$, BQ2962 | 2.900 | 3.000 | 3.100 | |
| | | | $V_{REG} = 2.5\text{ V}$, BQ2961 | 2.425 | 2.500 | 2.575 | |
| | | | $V_{REG} = 1.8\text{ V}$, BQ2961 | 1.746 | 1.800 | 1.854 | |
| I_{REG} | REG Current Output | $V_{DD} \geq 4\text{ V}$, $C_{REG} = 0.47\ \mu\text{F}$ | 0 | | 2 | mA | |
| $I_{REG_SC_Limit}$ | REG Output Short Circuit Current Limit | $REG = V_{SS}$, $C_{REG} = 0.47\ \mu\text{F}$ | 4 | | | mA | |
| R_{REG_PD} | REG pull-down resistor | REG is disabled. | 20 | 30 | 45 | k Ω | |
| Regulated Supply Output Enable, REG_EN | | | | | | | |
| V_{IH} | High-level Input | | 1.6 | | | V | |
| V_{IL} | Low-level Input | | | | 0.4 | V | |
| I_{LKG} | Input Leakage Current | $V_{IH} < 6\text{ V}$ | | | 0.1 | μA | |
| Regulated Supply Undervoltage Self-Disable | | | | | | | |
| V_{UVREG} | Undervoltage detection | Factory Configuration: 2.0 V to 3.5 V in 50 mV steps, $T_A = 25^\circ\text{C}$ | -50 | | 50 | mV | |
| V_{UVHYS} | Undervoltage Detection Hysteresis | | 250 | 300 | 400 | mV | |
| $t_{UVDELAY}$ | Undervoltage Detection Delay | | 4.5 | 6 | 7.5 | s | |
| V_{UVQUAL} | Cell voltage to qualify for UV detection | | | 0.5 | | V | |

(1) Specified by design. Not 100% tested in production.

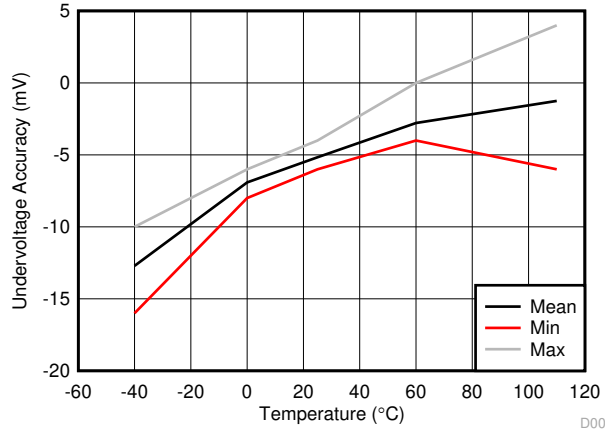
7.6 Typical Characteristics



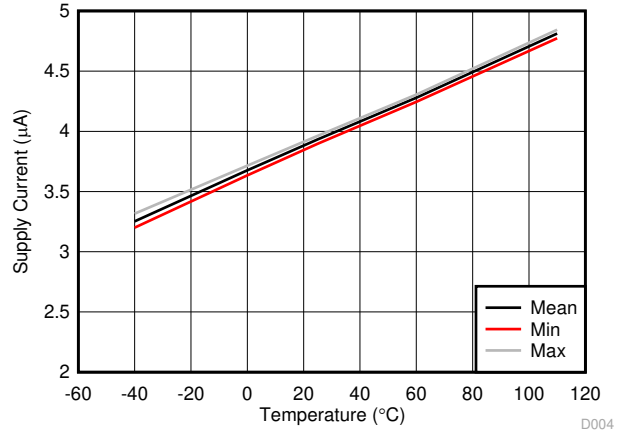
7-1. Overvoltage Threshold (V_{OV}) vs. Temperature



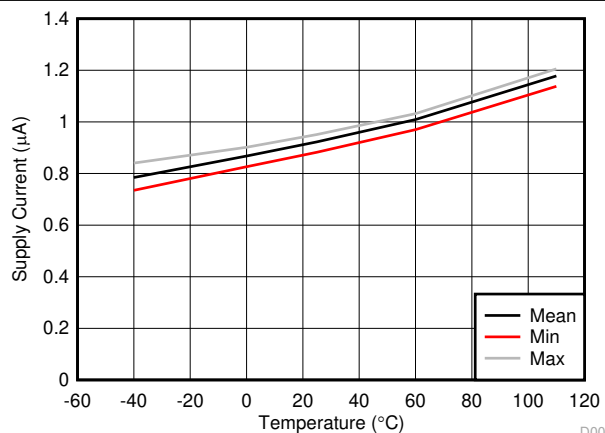
7-2. Hysteresis V_{HYS} vs. Temperature



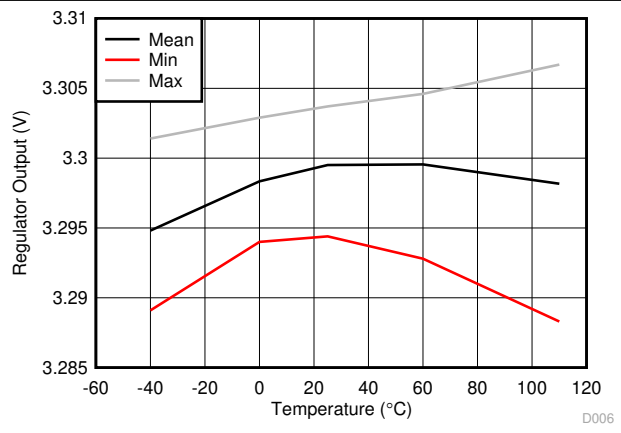
7-3. Undervoltage Accuracy



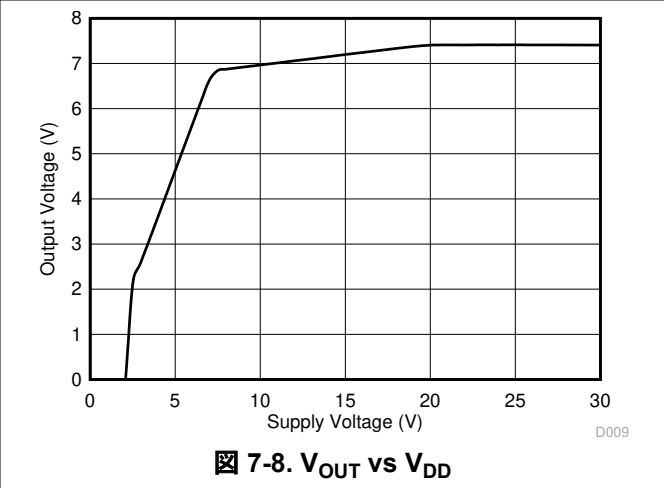
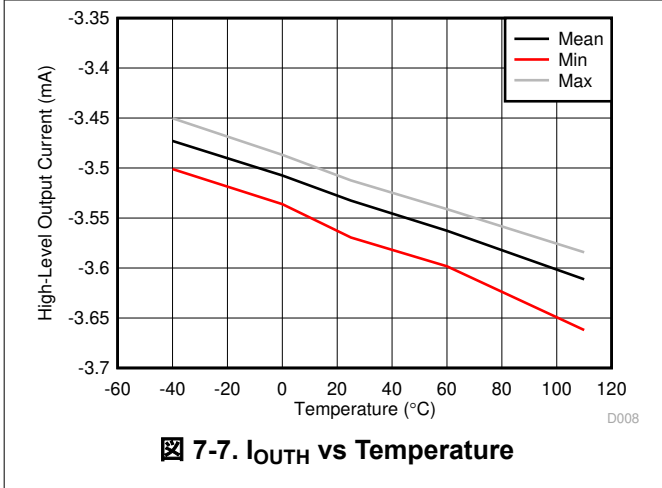
7-4. I_{DD} with Regulator On



7-5. I_{DD} with Regulator Off



7-6. Regulator Output Without Load



8 Detailed Description

8.1 Overview

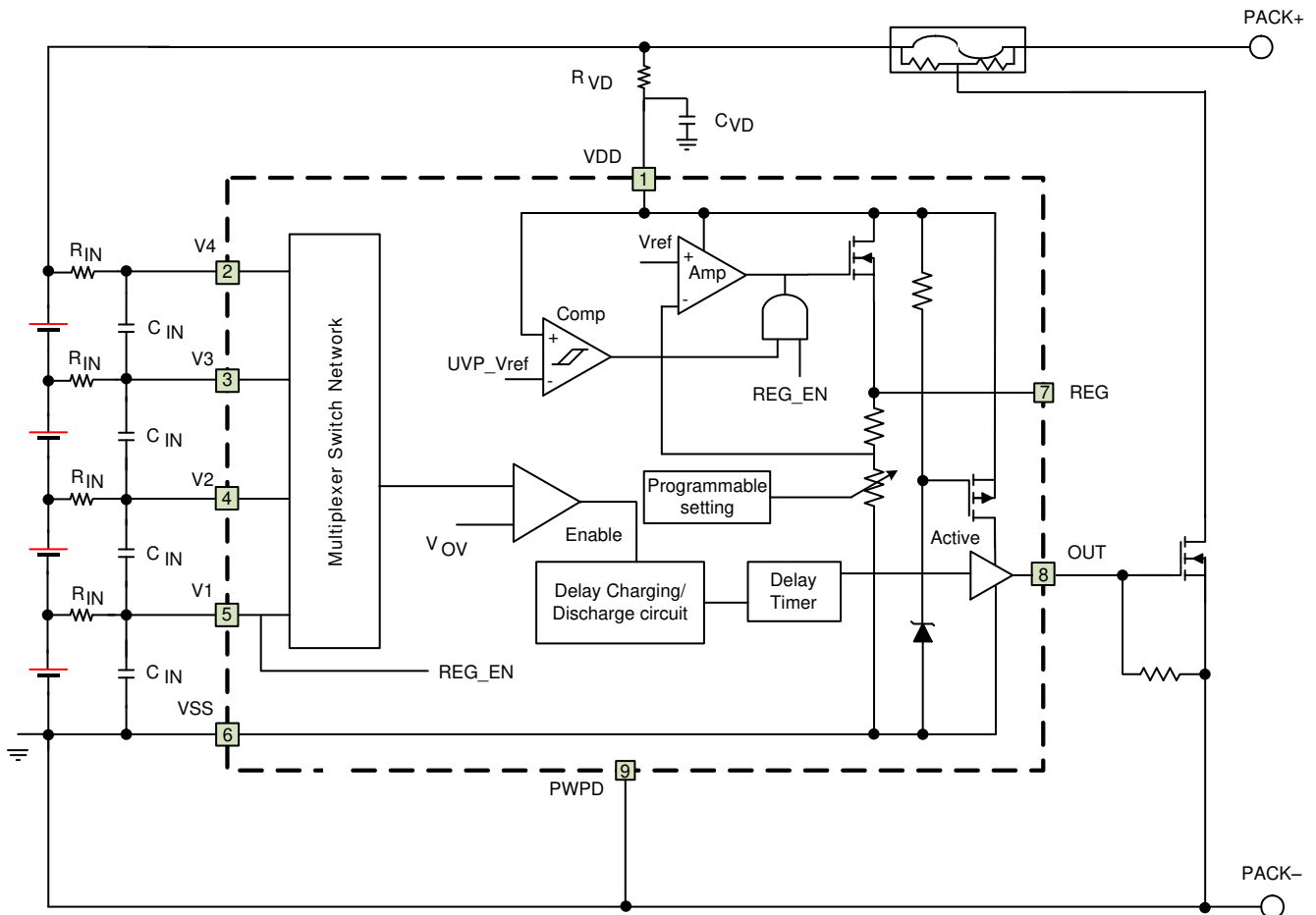
The BQ2961 and BQ2962 devices are second-level overvoltage (OV) protectors with a regulated output. Each cell is monitored independently by comparing the actual cell voltage to an overvoltage threshold V_{OV} . The overvoltage threshold is preprogrammed at the factory with a range between 3.85 V to 4.65 V.

The regulated output is enabled unless any of the cell voltages fall below the V_{UVREG} threshold. This threshold is preprogrammed at the factory with a range between 2 V to 2.8 (3.5 V for future BQ2962 options).

表 8-1. Programmable Parameters

| OVERVOLTAGE RANGE (V) | OVERVOLTAGE DELAY (s) | UNDERVOLTAGE RANGE (V) | REGULATOR (V) |
|----------------------------|-----------------------|---|---|
| 3.85 to 4.6 in 50-mV steps | 3, 4, 5.5, 6.5 | 2.0 to 2.8 (3.5 for future BQ2962 options) in 50-mV steps | 1.8, 2.5, 3.3 (BQ2961) 3.0, 3.15, 3.3 (BQ2962) |

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Pin Details

8.3.1.1 Input Sense Voltage, V_x

These inputs sense each battery cell voltage. A series resistor and a capacitor across the cell for each input is required for noise filtering and stable voltage monitoring.

8.3.1.2 Output Drive, OUT

This terminal serves as the fault signal output in active high.

8.3.1.3 Supply Input, VDD

This terminal is the unregulated input power source for the device. A series resistor is connected to limit the current, and a capacitor is connected to ground for noise filtering.

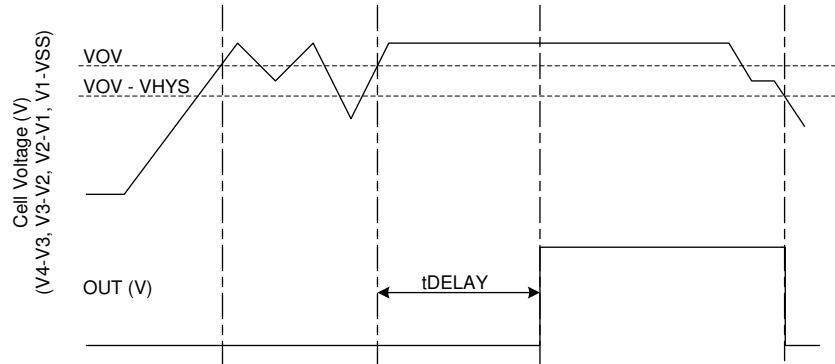
8.3.1.4 Regulated Supply Output, REG

This terminal is connected to an external capacitor and provides a regulated supply to power a circuit such as a real-time clock integrated circuit, or functions requiring a well-regulated supply. Maximum current load on this pin cannot exceed I_{REG} mA.

The REG output has protection for overcurrent, using a current limit protection circuit, and also detects and protects for excessive power dissipation due to short circuit of the external load. This pin requires a ceramic 1- μ F capacitor connection to VSS for improved stability, noise immunity, and ESD performance of the supply output. This capacitor must be placed close to the REG and VSS pins for connection.

8.3.2 Overvoltage Sensing for OUT

In the BQ296xxx device, each cell is monitored independently. Overvoltage is detected by comparing the actual cell voltage to a protection voltage reference, V_{OV} . If any cell voltage exceeds the programmed OV value, an internal timer circuit is activated. This timer circuit causes a factory pre-programmed fixed delay before the OUT terminal goes from inactive to active state.



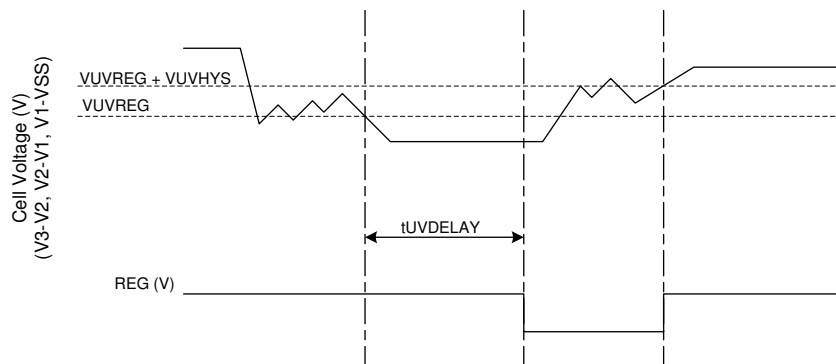
8-1. Timing for Overvoltage Sensing for OUT

8.3.3 Regulated Output Voltage and REG_EN Pin

For BQ2961, there are three factory-preprogrammed options for the regulated output voltage, 3.3 V, 2.5 V, and 1.8 V. For BQ2962, the regulated output voltage options are 3.3 V, 3.15 V, and 3.0 V. Potentially, the BQ2962xy device can provide other regulated voltage output between 3.3 V to 3.0 V. Contact Texas Instruments for details.

At power up, the regulated output is on by default. If any cell voltage is below V_{UVREG} at device power up, the regulated output will remain on until the t_{UV_DELAY} time has passed, the regulated output turns off after the delay time.

During discharge, if any cell voltage falls below the V_{UVREG} threshold for t_{UV_DELAY} time, the regulated output is self-disabled. The regulated output turns on again when all the cell voltages are above $V_{UVREG} + V_{UVHYS}$.



8-2. REG Output Timing

8.4 Device Functional Modes

8.4.1 NORMAL Mode

When all of the cell voltages are below the V_{OV} threshold AND above V_{UVREG} threshold, the device operates in NORMAL mode. The device monitors the differential cell voltages connected across (V1–VSS), (V2–V1), (V3–V2), and (V4–V3). The OUT pin is inactive in this mode. The regulated output is always enabled for BQ2961.

8.4.2 OVERVOLTAGE Mode

OVERVOLTAGE mode is detected if any of the cell voltages exceed the overvoltage threshold, V_{OV} , for a configured OV delay time. The OUT pin is activated after a delay time preprogrammed at the factory. The OUT

pin will pull high internally. Then an external FET is turned on, shorting the fuse to ground, which allows the battery and/or charger power to blow the fuse. When all of the cell voltages fall below $(V_{OV} - V_{HYS})$, the device returns to NORMAL mode. The regulated output (if enabled) remains on in this mode.

8.4.3 UNDERVOLTAGE Mode

The UNDERVOLTAGE mode is detected if any of the cell voltage across $(V1-VSS)$, $(V2-V1)$, $(V3-V2)$, or $(V4-V3)$ is below the V_{UVREG} threshold for t_{UV_DELAY} time. In this mode, the regulated output is disabled. To return to the NORMAL mode, all the cell voltages must be above $(V_{UVREG} + V_{UVHYS})$.

For a low cell configuration, V_n pin can be shorted to the (V_{n-1}) pin. The device ignores any differential cell voltage below V_{UVQUAL} threshold for undervoltage detection.

8.4.4 CUSTOMER TEST MODE

The Customer Test Mode (CTM) helps to reduce test time for checking the overvoltage delay-timer parameter once the circuit is implemented into the battery pack. To enter CTM, the VDD pin should be set at least 10 V higher than V3 (see [Figure 8-3](#)). The delay timer is greater than 10 ms, but considerably shorter than the timer delay in normal operation. To exit CTM, remove the VDD to VC3 voltage differential of 10 V, so that the decrease in the value automatically causes an exit.

注意

Avoid exceeding any Absolute Maximum Voltages on any pins when placing the device into CTM. Also avoid exceeding Absolute Maximum Voltages for the individual cell voltages $(V3-V2)$, $(V2-V1)$ and $(V1-VSS)$. Stressing the pins beyond the rated limits can cause permanent damage to the device.

[Figure 8-3](#) shows the timing for the Customer Test Mode.

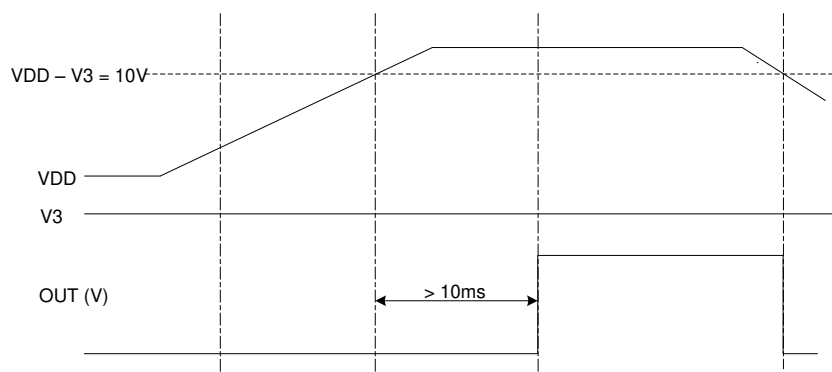


Figure 8-3. Timing for Customer Test Mode

[Figure 8-4](#) shows the measurement for current consumption of the product for both VDD and V_x .

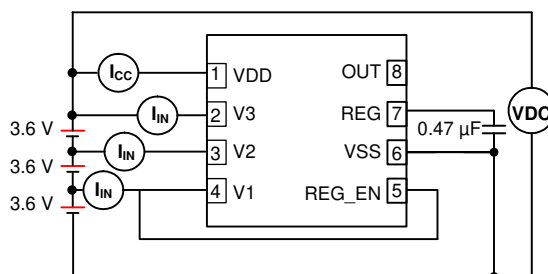


Figure 8-4. Configuration for Integrated Circuit Current Consumption Test

9 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The BQ296xxx family of second-level protectors is used for overvoltage protection of the battery pack in the application. A regulated output is available to drive a small circuit with maximum I_{REG} loading. The device OUT pin is active high, which drives a NMOS FET that connects the fuse to ground in the event of a fault condition. This provides a shorted path to use the battery and/or charger power to blow the fuse and cut the power path.

9.2 Typical Application

Application Schematic shows the recommended reference design components.

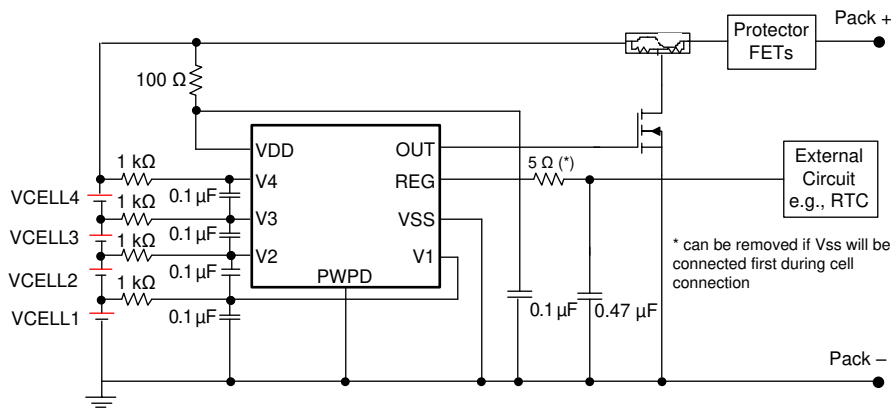


图 9-1. Application Schematic

9.2.1 Design Requirements

注

Changes to the ranges shown in 表 9-1 will impact the accuracy of the cell measurements.

表 9-1. Parameters

| PARAMETER | EXTERNAL COMPONENT | MIN | NOM | MAX | UNIT |
|------------------------------------|--------------------|------|------|------|-----------|
| Voltage monitor filter resistance | R_{IN} | 900 | 1000 | 4700 | Ω |
| Voltage monitor filter capacitance | C_{IN} | 0.01 | 0.1 | 1.0 | μF |
| Supply voltage filter resistance | R_{VD} | 0.1 | — | 1 | $K\Omega$ |
| Supply voltage filter capacitance | C_{VD} | — | 0.1 | 1.0 | μF |
| REG output capacitance | C_{REG} | 0.47 | 1 | — | μF |

注

The device is calibrated using an R_{IN} value = 1 k Ω . Using a value other than the recommended value changes the accuracy of the cell voltage measurements and V_{OV} trigger level.

9.2.2 Detailed Design Procedure

注

The device VSS must be connected first during PCB test or cell attachment. Failure to do so can damage the REG pin.

1. If the VSS pin cannot be connected first, it is required to add a resistor of a minimum of 5 Ω to a maximum of 10 Ω (a 5- Ω resistor is used in the reference schematic, [Figure 9-2](#)) in series with the REG capacitor. When VSS is floating, the REG capacitor always charges up to the VDD voltage. When VSS is finally connected, the REG capacitor will be discharged. Adding a small resistor in series reduces the current strength and avoids any potential damage to the REG pin. The 5- Ω resistor can be placed in series with the REG connect circuit (as shown in [Figure 9-2](#)) or in series of the REG capacitor (as shown in [Figure 9-3](#)). Placing the resistor in series with the REG circuit results in a small drop of V_{REG} (for example: max loading of I_{REG} mA with a 5- Ω resistor will drop 5 mV on V_{REG}), but such a connection can protect against rush current discharge from a REG capacitor or an external filter capacitor connected to the REG pin. Placing the resistor in series with the REG capacitor is an alternative to avoiding an additional drop in V_{REG} if the filter capacitor used by the external circuit is much smaller than the REG capacitor.
2. After VSS is connected, the device allows a random cell connection to the Vx pin.
3. The cell should be connected to the lower V_n pin; the unused V_n pin should be shorted to the (V_{n-1}) pin. See [Figure 9-2](#) for details.

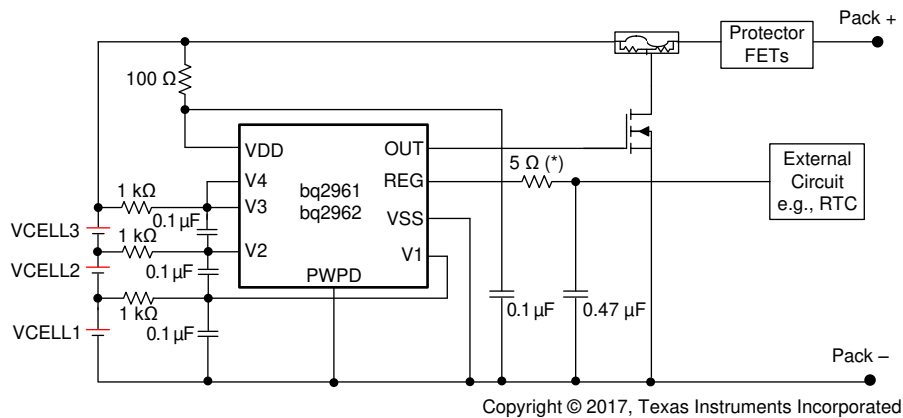
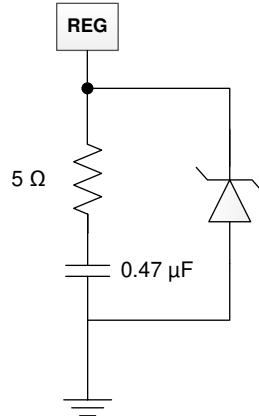


Figure 9-2. 3-Series BQ2961 and BQ2962 Schematic

4. A Zener diode can be added to the REG pin to VSS, as shown in [Figure 9-3](#). This is recommended to protect the circuit connected to the REG pin if floating VSS in the field is a risk concern. When VSS is floating (during cell connection when VSS is not connected first or in a system fault with a broken BAT– wire), the REG voltage always pulls up to VDD. In a 4-series configuration, the REG voltage can reach approximately 16 V with VSS floating. Adding a Zener diode clamps the REG voltage to a safe level for the external circuits connected to the REG pin. Having the Zener diode can also protect the external circuits if the REG pin is shorted to the OUT pin or any other high-voltage output terminal. If a Zener diode is used, TI recommends putting the diode on the battery side with the BQ296xxx device to allow protection on the REG pin, as well as the circuit connected to REG under the floating VSS condition. The resistor in series with the REG pin is not required in this case.

The 5-Ω resistor limits the rush current discharge from the capacitor during cell connection when Vss is not connected first.

This resistor is not required if Vss is connected first in the cell connection sequence.



Loss of Vss connection or REG shorted to high voltage can bring the REG above the regulated range. This optional zener clamp can protect the downstream circuit under such an event.

图 9-3. 5-V Zener Diode

9.2.3 Application Curves

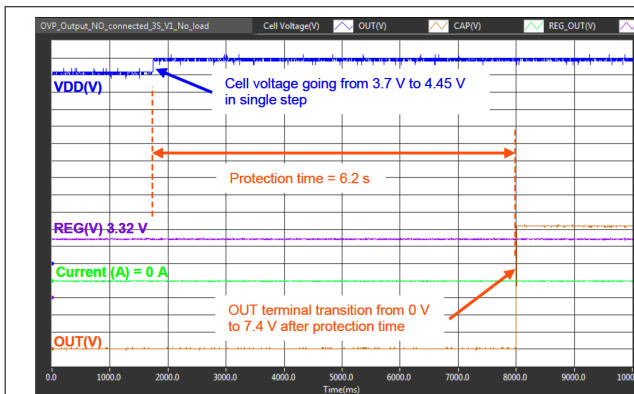


图 9-4. Overvoltage Protection

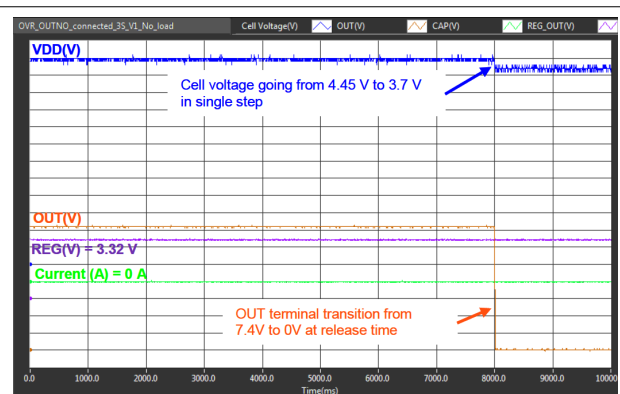


图 9-5. Overvoltage Protection Release

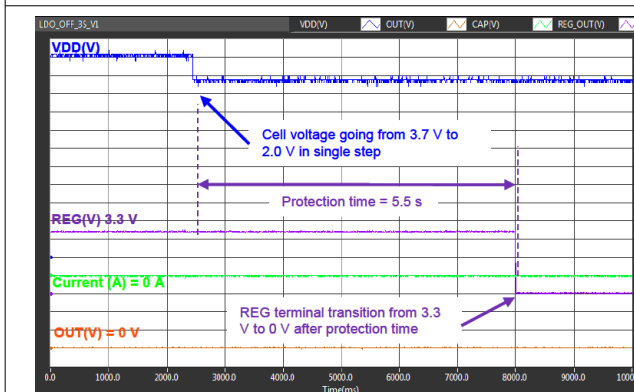


图 9-6. Undervoltage Detection to Turn Off the Regulator

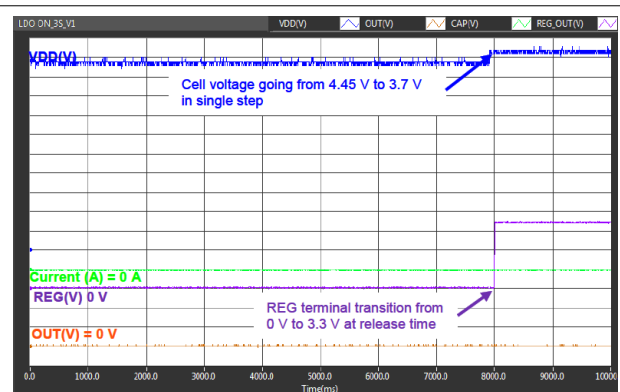


图 9-7. Undervoltage Release to Switch On the Regulator

10 Power Supply Recommendations

The maximum power is 20 V for BQ2961 and BQ2962 on VDD.

注

Connect VSS first during power-up.

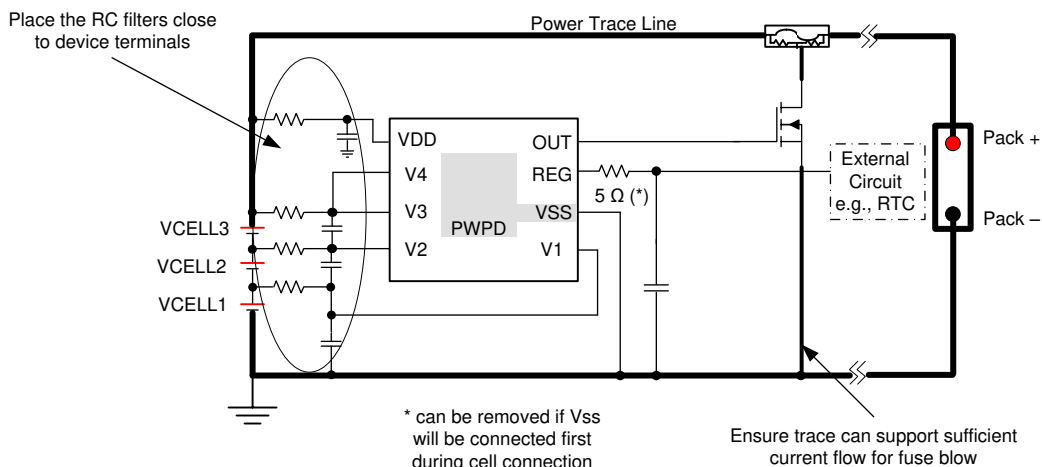
11 Layout

11.1 Layout Guidelines

Use the following layout guidelines:

1. Ensure the RC filters for the Vx pins and VDD pin are placed as close as possible to the target terminal, reducing the tracing loop area.
2. The capacitor for REG should be placed close to the device terminals.
3. Ensure the trace connecting the fuse to the gate, source of the NFET to the Pack– is sufficient to withstand the current during a fuse blown event.

11.2 Layout Example



☒ 11-1. Layout Example

12 Device and Documentation Support

12.1 Third-Party Products Disclaimer

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To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 サポート・リソース

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12.4 Trademarks

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12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| BQ296100DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6100 | Samples |
| BQ296100DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6100 | Samples |
| BQ296103DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6103 | Samples |
| BQ296103DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6103 | Samples |
| BQ296106DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6106 | Samples |
| BQ296106DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6106 | Samples |
| BQ296107DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6107 | Samples |
| BQ296107DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6107 | Samples |
| BQ296111DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 110 | 6111 | Samples |
| BQ296111DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6111 | Samples |
| BQ296112DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 110 | 6112 | Samples |
| BQ296112DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 110 | 6112 | Samples |
| BQ296113DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6113 | Samples |
| BQ296113DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6113 | Samples |
| BQ296114DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6114 | Samples |
| BQ296114DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6114 | Samples |
| BQ296115DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6115 | Samples |
| BQ296202DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6202 | Samples |
| BQ296202DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6202 | Samples |
| BQ296203DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6203 | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| BQ296203DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6203 | Samples |
| BQ296212DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 110 | 6212 | Samples |
| BQ296212DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 110 | 6212 | Samples |
| BQ296213DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6213 | Samples |
| BQ296213DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6213 | Samples |
| BQ296215DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6215 | Samples |
| BQ296215DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6215 | Samples |
| BQ296216DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6216 | Samples |
| BQ296216DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6216 | Samples |
| BQ296217DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6217 | Samples |
| BQ296217DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6217 | Samples |
| BQ296221DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 110 | 6221 | Samples |
| BQ296221DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6221 | Samples |
| BQ296222DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6222 | Samples |
| BQ296222DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6222 | Samples |
| BQ296223DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6223 | Samples |
| BQ296223DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6223 | Samples |
| BQ296224DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6224 | Samples |
| BQ296224DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6224 | Samples |
| BQ296226DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6226 | Samples |
| BQ296226DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6226 | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| BQ296227DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6227 | Samples |
| BQ296228DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6228 | Samples |
| BQ296228DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6228 | Samples |
| BQ296229DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6229 | Samples |
| BQ296229DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6229 | Samples |
| BQ296230DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6230 | Samples |
| BQ296230DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6230 | Samples |
| BQ296231DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6231 | Samples |
| BQ296231DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6231 | Samples |
| BQ296232DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6232 | Samples |
| BQ296232DSGT | ACTIVE | WSON | DSG | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6232 | Samples |
| BQ296233DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6233 | Samples |
| BQ296234DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6234 | Samples |
| BQ296235DSGR | ACTIVE | WSON | DSG | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 110 | 6235 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| BQ296100DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296100DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296103DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296103DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296106DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296106DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296107DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296107DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296111DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296111DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296112DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296112DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296113DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296113DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296114DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296114DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| BQ296115DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296202DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296202DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296203DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296203DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296212DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296212DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296213DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296213DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296215DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296215DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296216DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296216DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296217DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296217DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q2 |
| BQ296221DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296221DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296222DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296222DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296223DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296223DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296224DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296224DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296226DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296226DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296227DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296228DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296228DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296229DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296229DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296230DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296230DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296231DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296231DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296232DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296232DSGT | WSON | DSG | 8 | 250 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296233DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296234DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |
| BQ296235DSGR | WSON | DSG | 8 | 3000 | 180.0 | 8.4 | 2.3 | 2.3 | 1.15 | 4.0 | 8.0 | Q3 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| BQ296100DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296100DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296103DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296103DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296106DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296106DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296107DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296107DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296111DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296111DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296112DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296112DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296113DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296113DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296114DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296114DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296115DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296202DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| BQ296202DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296203DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296203DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296212DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296212DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296213DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296213DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296215DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296215DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296216DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296216DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296217DSGR | WSON | DSG | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| BQ296217DSGT | WSON | DSG | 8 | 250 | 182.0 | 182.0 | 20.0 |
| BQ296221DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296221DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296222DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296222DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296223DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296223DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296224DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296224DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296226DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296226DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296227DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296228DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296228DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296229DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296229DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296230DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296230DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296231DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296231DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296232DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296232DSGT | WSON | DSG | 8 | 250 | 210.0 | 185.0 | 35.0 |
| BQ296233DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296234DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |
| BQ296235DSGR | WSON | DSG | 8 | 3000 | 210.0 | 185.0 | 35.0 |

GENERIC PACKAGE VIEW

DSG 8

WSON - 0.8 mm max height

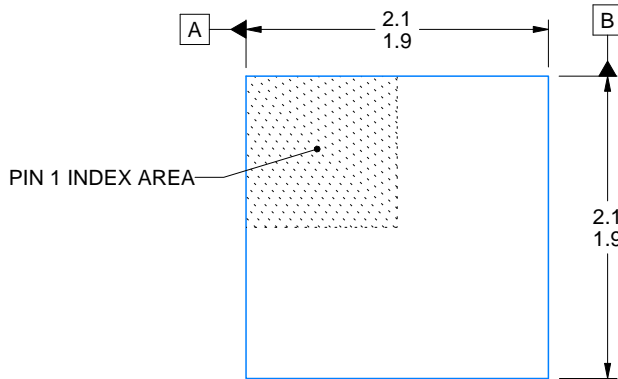
2 x 2, 0.5 mm pitch

PLASTIC SMALL OUTLINE - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



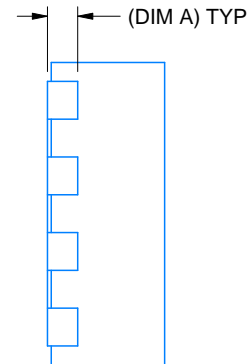
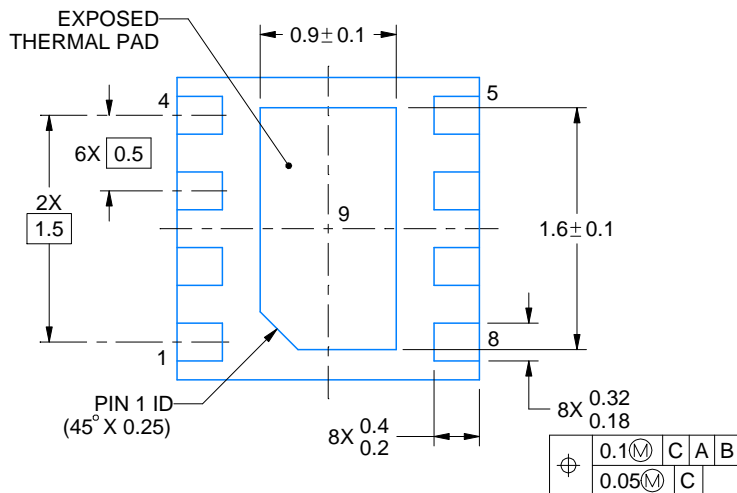
4224783/A



ALTERNATIVE TERMINAL SHAPE TYPICAL



| SIDE WALL METAL THICKNESS DIM A | |
|---------------------------------|----------|
| OPTION 1 | OPTION 2 |
| 0.1 | 0.2 |



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NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

DSG0008A

WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
SCALE:20X



SOLDER MASK DETAILS

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NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DSG0008A

WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 9:
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:25X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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